



NOTES:

THESE SURFACES TO BE FREE OF SEAMS.

CHAMFER DENOTES PACKAGE PIN 1 ORIENTATION.

TRAY VACUUM PICKUP METHOD REQUIRES A 28mm SQUARE (MINIMUM) WALLED PICKUP AREA, LOCATED IN THE CENTER OF THE TRAY.

- N REFERS TO PACKAGE LEAD COUNTS SUPPORTED, FULLY POPULATED PACKAGE
- TOTAL USABLE CELLS $N3 = N1 \times N2$.
- PACKAGE INTERFACE CONTROLLED BY PACKAGE DESIGN AND LEAD FORM.
- NON-TABULATED DIMENSIONS HAVE A TOLERANCE OF $.X=\pm 0.25$ $.XX=\pm 0.15$, ANGLES ± 0.5 °
- ALL DIMENSIONS ARE IN MILLIMETERS.
- INTERPRET DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ANSI Y14.5M-1982.



 $hsigma \wedge \wedge$ xxx is the maximum operating temperature the empty tray can BE SUBJECTED TO FOR 48 CONTINUOUS HOURS WITHOUT VIOLATING THE DIMENSIONAL TOLERANCE OF THE TRAY.



/11\ N4 INDICATES PACKAGE SIZE/LEAD COUNT ACCOMMODATED.

- 12 DIMENSIONS M. M1, M2, AND M3 DEFINE THE CENTER LINES FOR THE CELL SITES.
- 13 ALL EXTERNAL TRAY SURFACES WHICH MAY COME IN CONTACT WITH THE DRY PACK BAGS SHALL BE FREE OF SHARP EDGES.
- 14 ALL TRAY MEASUREMENTS ARE TO BE MADE WITH THE TRAY UN-RESTRICTED.
- 15 AN ADDITIONAL ROW CAN BE ADDED TO VARIATION AA. THIS ADDITIONAL ROW WOULD CHANGE N2 TO 3, N3 TO 12 MAX, AND M2 TO 30.80. THIS MIDDLE ROW CAN BE DEPOPULATED IN ANY MANNER.



THESE SCALLOPS PRESENT ON 2 X 2 MATRIX ONLY.

THESE SCALLOPS PRESENT ON 4 X 2 MATRIX ONLY.

JEDEC THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JC-11 Solid State COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN TH Product Outline ELECTRONICS INDUSTRY: CHANGES ARE LIKELY TO OCCUR						THE
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BALL GRID ARRAY

VARIATION DIMENSIONS ARE IN MILLIMETERS							
VARIATION	N4 PACKAGE BODY	SIZE	N (LEAD COUNT)			x N2 MATRIX	
AA	25MM X 25M	1		256-361-		I.	X 2
AA	27MM X 27N	J		324-441-		i i	X 2
AA	29MM X 29M	1M	,	361-484-	/84	4	X 2
AB	31MM X 31M	IM .		1 00–576–	900	2	X 2
AB	33MM X 33MM,32.5MN	1 X 32.5MM	441-	484-625-6	76-1024	2	X 2
AB	35MM X 35M	1M	5	29-729-	1156	2	X 2
AB	37.5MM X 37.	5MM	6	25-841-	1369	2	X 2
AB	40MM X 40M	1M	(676-961-	1521	2	X 2
AB	42.5MM X 42.5	5мм	7	84-1089-	1764	2	X 2
AA	25MM X 21M	1M	•	224-304-	480	4	X 2
AB	32.5MM X 25	;		336-475-			X 2
JEDEC THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JC-11							
JEDE Solid St Product C	cate COMMITTEE	STERED OUTLINE AND REFLECTS CS INDUSTRY; C	A PRO	DUCT WITH	ANTICIPAT	ED USAGE I	N THE
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S _{YMBOL}	DIMENSIONS ARE IN M	∐N	DIMENSIONS ARE IN MILLIMETERS			NOT	
	. AA		$-\frac{N}{2}$	AB			
$^{\circ}$	MIN NOM	MAX	E E	MIN	NOM	MAX	E
М	21.75 BSC		12	29.20 BSC			12
M1	22.15 BSC	12		12			
M2	31.80 BSC	12	45.60 BSC			12	
мЗ	30.80 BSC	12	77.50 BSC			12	
N1	4 COLUMNS						
N2	2 ROWS				2 ROWS		
N3	8		5		4		5
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